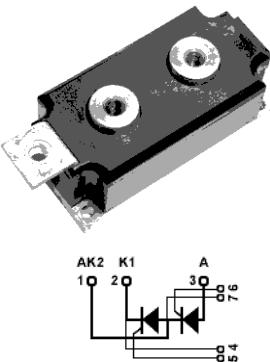


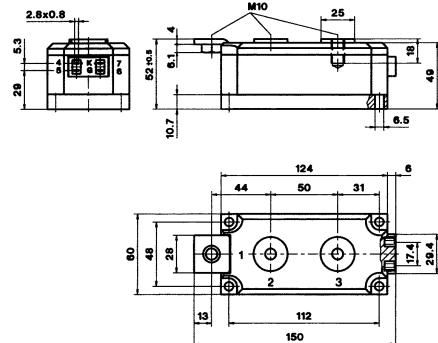
STT500

Thyristor-Thyristor Modules



Type	V _{RSM}	V _{RRM}
	V _{DSM}	V _{DRM}
	V	V
STT500GK08	900	800
STT500GK12	1300	1200
STT500GK14	1500	1400
STT500GK16	1700	1600
STT500GK18	1900	1800

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit
I_{TRMS} , I_{FRMS} I_{TAVM} , I_{FAVM}	$T_{VJ}=T_{VJM}$ $T_C=85^\circ C$; 180° sine	785 500	A
I_{TSM} , I_{FSM}	$T_{VJ}=45^\circ C$ $V_R=0$	15000 16000	A
	$T_{VJ}=T_{VJM}$ $V_R=0$	13000 14400	
$\int i^2 dt$	$T_{VJ}=45^\circ C$ $V_R=0$	1125000 1062000	$A^2 s$
	$T_{VJ}=T_{VJM}$ $V_R=0$	845000 813000	
$(di/dt)_{cr}$	$T_{VJ}=T_{VJM}$ $f=50Hz$, $t_p=200\mu s$ $V_D=2/3V_{DRM}$ $I_G=1A$ $di_G/dt=1A/\mu s$	repetitive, $I_T=960A$ non repetitive, $I_T=I_{TAVM}$	100 500
			A/ μs
$(dv/dt)_{cr}$	$T_{VJ}=T_{VJM};$ $R_{GK}=\infty$; method 1 (linear voltage rise)	1000	V/ μs
P_{GM}	$T_{VJ}=T_{VJM}$ $I_T=I_{TAVM}$	120 60	W
P_{GAV}		20	W
V_{RGM}		10	V
T_{VJ} T_{VJM} T_{stg}		-40...+140 140 -40...+125	°C
V_{ISOL}	50/60Hz, RMS $I_{ISOL}\leq 1mA$	3000 3600	V~
M_d	Mounting torque (M6) Terminal connection torque (M8)	4.5-7/40-60 11-13/97-115	Nm/lb.in.
Weight	Typical including screws	940	g

STT500

Thyristor-Thyristor Modules

Symbol	Test Conditions	Characteristic Values	Unit
I_{RRM}	$T_{VJ}=T_{VJM}$; $V_R=V_{RRM}$	40	mA
V_T	$I_T=1200A$; $T_{VJ}=25^\circ C$	1.3	V
V_{TO}	For power-loss calculations only ($T_{VJ}=T_{VJM}$)	0.8	V
r_T		0.38	$m\Omega$
V_{GT}	$V_D=6V$; $T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	2 3	V
I_{GT}	$V_D=6V$; $T_{VJ}=25^\circ C$ $T_{VJ}=-40^\circ C$	300 400	mA
V_{GD}	$T_{VJ}=T_{VJM}$; $V_D=2/3V_{DRM}$	0.25	V
I_{GD}	$T_{VJ}=T_{VJM}$; $V_D=2/3V_{DRM}$	10	mA
I_L	$T_{VJ}=25^\circ C$; $t_p=30\mu s$; $V_D=6V$ $I_G=1A$; $dI/dt=1A/\mu s$	400	mA
I_H	$T_{VJ}=25^\circ C$; $V_D=6V$; $R_{GK}=\infty$	300	mA
t_{gd}	$T_{VJ}=25^\circ C$; $V_D=1/2V_{DRM}$ $I_G=1A$; $dI/dt=1A/\mu s$	2	us
t_q	$T_{VJ}=T_{VJM}$; $I_T=500A$; $t_p=200\mu s$; $-dI/dt=10A/\mu s$ $V_R=100V$; $dv/dt=50V/\mu s$; $V_D=2/3V_{DRM}$	typ. 350	us
R_{thJC}	DC current	0.072	K/W
R_{thJK}	DC current	0.096	K/W
ds	Creeping distance on surface	12.7	mm
da	Creepage distance in air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

FEATURES

- * International standard package
- * Direct copper bonded Al₂O₃-ceramic with copper base plate
- * Planar passivated chips
- * Isolation voltage 3600 V~

APPLICATIONS

- * Motor control, softstarter
- * Power converter
- * Heat and temperature control for industrial furnaces and chemical processes
- * Lighting control
- * Solid state switches

ADVANTAGES

- * Simple mounting
- * Improved temperature and power cycling
- * Reduced protection circuits



STT500

Thyristor-Thyristor Modules

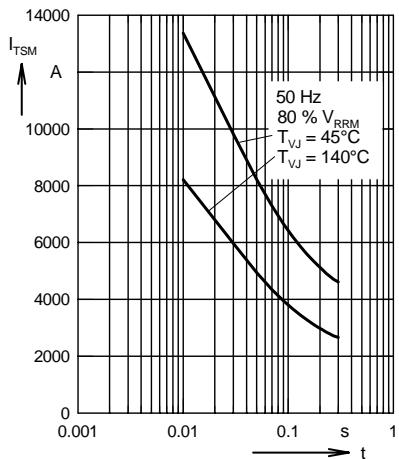


Fig. 1 Surge overload current
 I_{TSM} , I_{FSM} : Crest value, t : duration

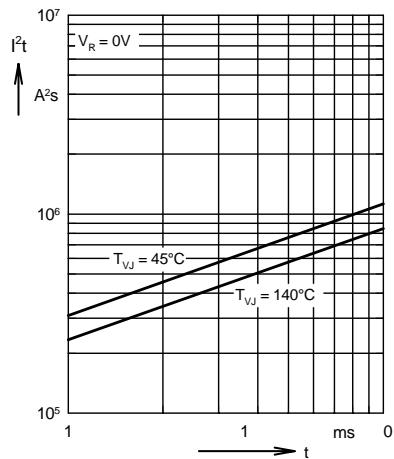


Fig. 2 $\int i^2 dt$ versus time (1-10 ms)

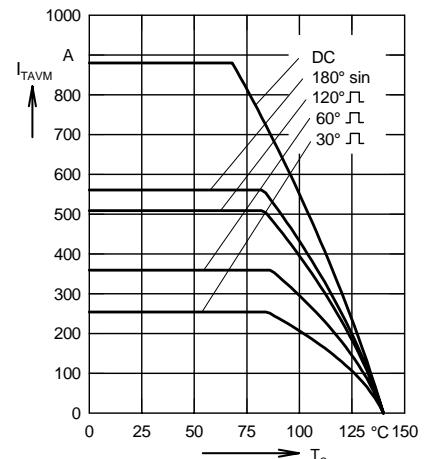


Fig. 3 Maximum forward current
at case temperature

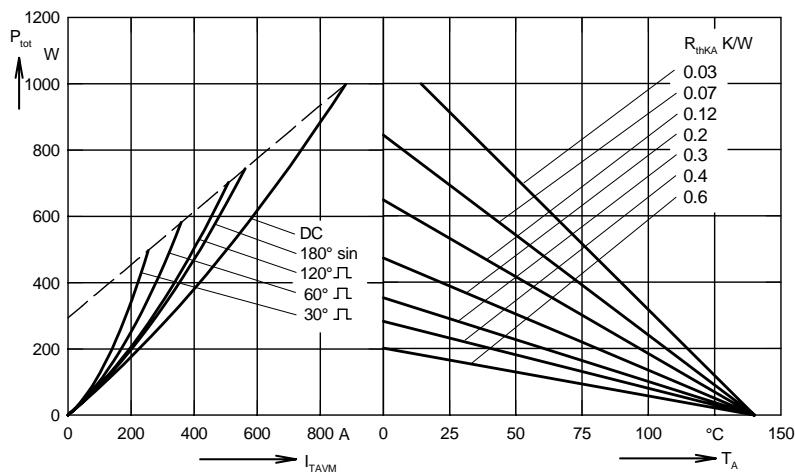


Fig. 4 Power dissipation versus on-state current and ambient temperature

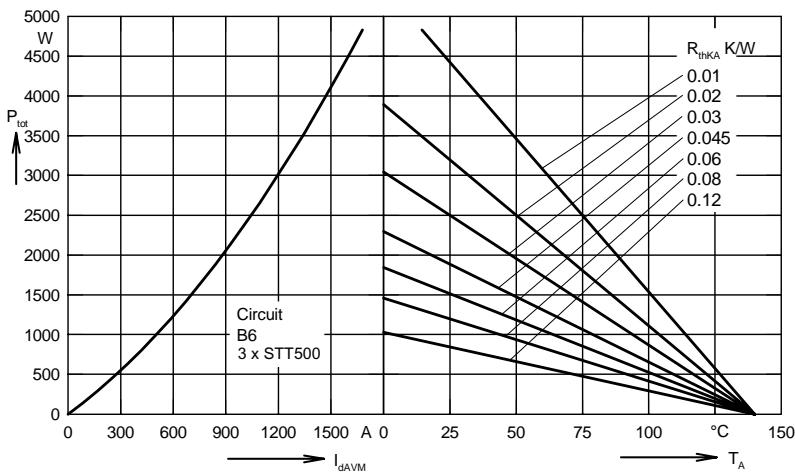


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current
and ambient temperature

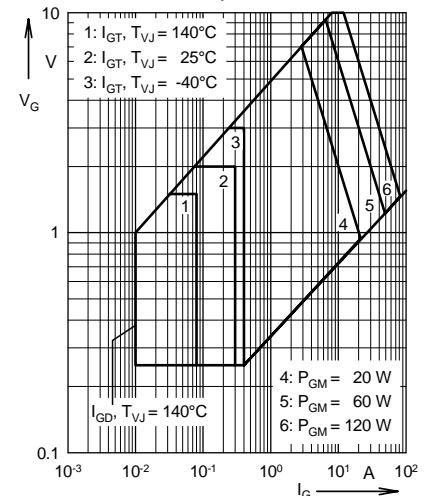


Fig. 5 Gate trigger characteristics

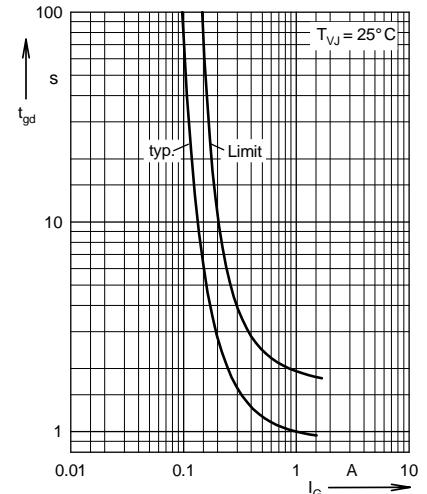


Fig. 7 Gate trigger delay time

STT500

Thyristor-Thyristor Modules

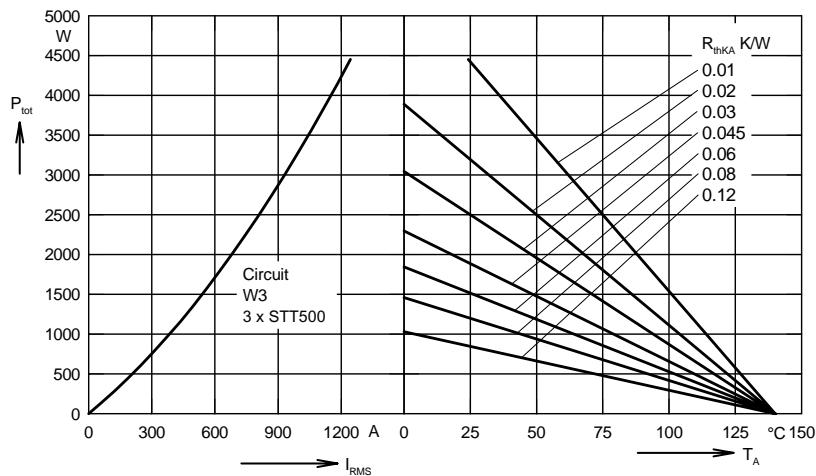


Fig. 8 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

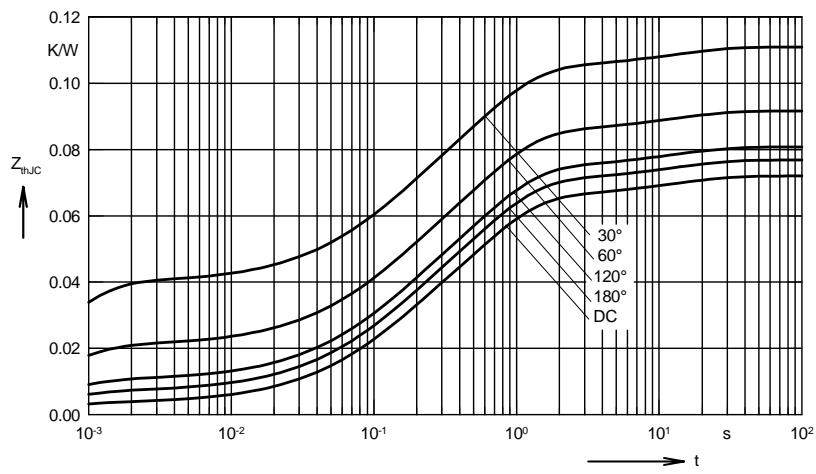


Fig. 9 Transient thermal impedance
junction to case (per thyristor)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.072
180°C	0.0768
120°C	0.081
60°C	0.092
30°C	0.111

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0054
2	0.0186	0.098
3	0.0432	0.54
4	0.0067	12

Fig.10 Transient thermal impedance
junction to heatsink (per thyristor)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.096
180°C	0.1
120°C	0.105
60°C	0.116
30°C	0.135

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0054
2	0.0186	0.098
3	0.0432	0.54
4	0.0067	12
5	0.024	12

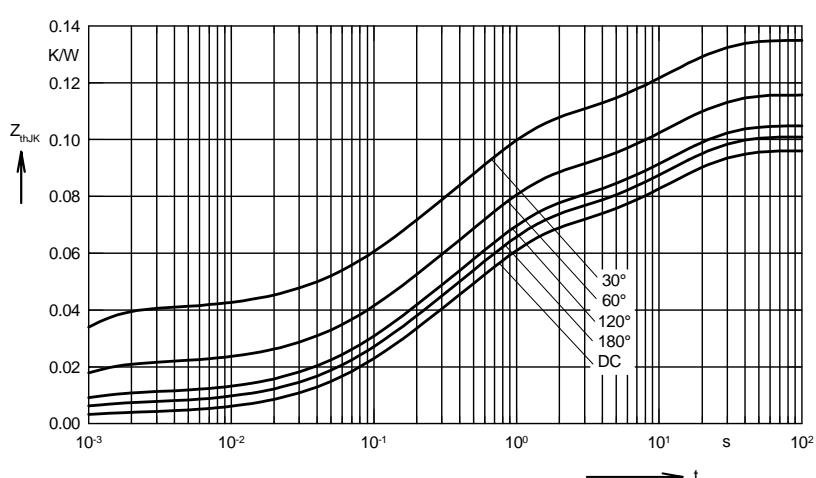


Fig. 10 Transient thermal impedance
junction to heatsink (per thyristor)